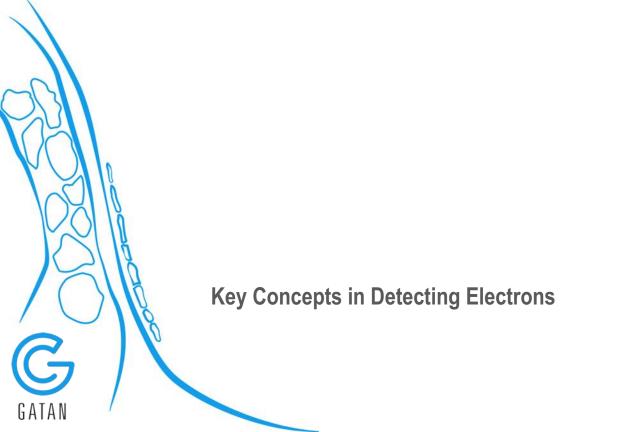
# **Detection Technologies for Cryo-Electron Microscopy**

 $S^2C^2$  Workshop – Cryo-EM Training for Beginners Christopher Booth Gatan Inc.

Jan 22, 2019







# **Key Concepts in Detecting Electrons**

- CMOS and CCD
- "indirect" vs direct detection cameras
- Sensitivity
- Linearity and dynamic range
- Dynamic range
- Pixel size and field of view
- Electron counting
- Co-incidence loss



#### **Recording Images In Electron Microscopy**

A little bit of history

- Oldest recording medium: photographic film
- 1970: Charge coupled device (CCD) was invented
- 1976: CCD camera was used for astronomy
- 1982: 100 x 100 CCD was directly exposed to 100 kV electrons...radiation damage
- 1988: 576 x 382 CCD used with scintillator and optical coupler
- 1990: Gatan made the world's first commercial CCD camera
- 2002: 128 x 128 direct detection camera developed
- 2008 2009: commercial complementary metal-oxide semiconductor (CMOS) cameras and radiation hard CMOS cameras were introduced

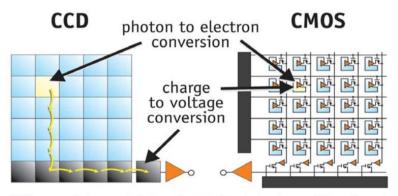




#### CCD vs. CMOS

Both CCD and CMOS use photo diodes to convert photons to electrons, the difference is how they store charge and transfer it.

- · CCD: Charge is transferred between neighboring cells, and read-out
- CMOS: Charge immediately converted to voltage (read out with digital output)

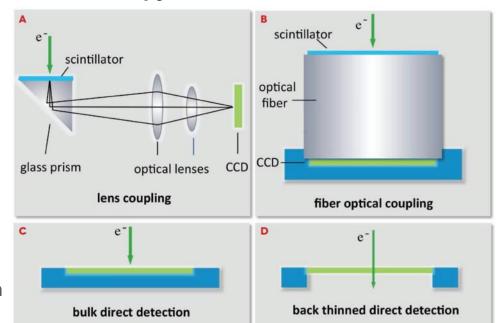




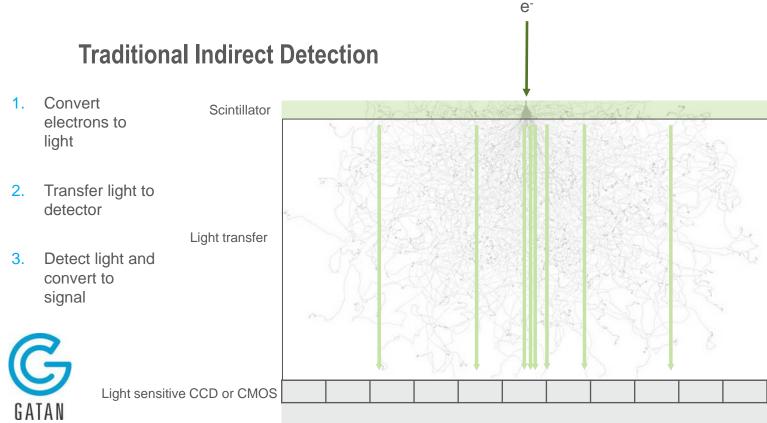
CCDs move photogenerated charge from pixel to pixel and convert it to voltage at an output node. CMOS imagers convert charge to voltage inside each pixel.

## **Detectors in Electron Microscopy**

- A. Optically coupled
- B. Fiber-optic coupling
- C. Direct detection
- D. Transmission direct detection







#### **Direct Detection**

- 1. Convert electrons to light
- 2. Transfer light to detector
- 3. Detect electron and convert to signal



Radiation hard CMOS

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# **Transmission Direct Detection**

- 4. Convert electrons to light
- 2. Transfer light to detector
- Detect electron and convert to signal



Radiation hard, thinned CMOS

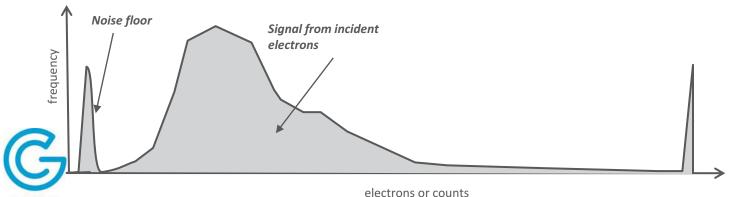


Minimize back

scattered electrons that add noise

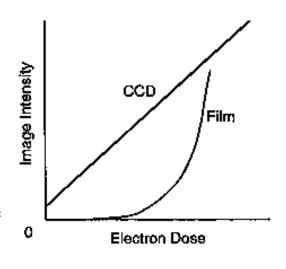
## Sensitivity

- Minimum detectable signal in terms of the number of incident electrons.
- Single-electron sensitivity
  - if the gain of the system is such that the output of a single incident electron is above the noise floor



### Linearity

- Relationship between output (image intensity in digital units) and the input (number of incident electrons).
- CMOS and CCDS are much more linear than film
- Counted cameras have a special kind of non-linearity called co-incidence loss

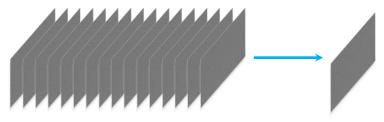




## **Dynamic Range**

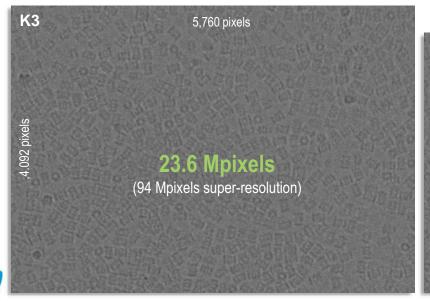
**Dynamic range:** The range of values that can be distinguished between a maximum level (saturation) and zero (noise)

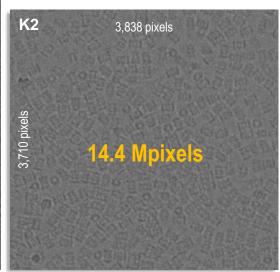
- Driven by combination of max allowable charge in each and noise floor
  - One pixel can have 16 bit dynamic range (values between 0 16000)
- Used to be a very important factor for cameras, now frame rate is much more important
  - A camera with only 12 bit dynamic range (0 4095) might accumulate 40 frames in a second.
  - 4095 x 20 = 163,800 counts of dynamic range





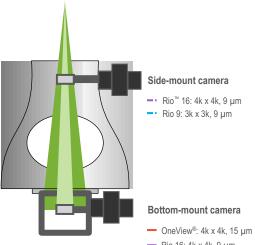
# **How Many Pixels are Enough?**



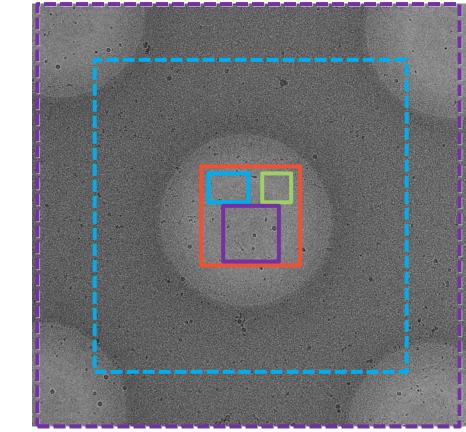




# **How Important is FOV?**



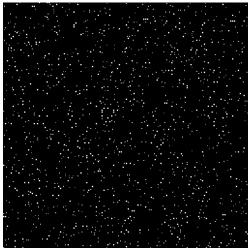
- Rio 16: 4k x 4k, 9 μm
- K3™: 6k x 4k, 5 μm
- K2®: 4k x 4k, 5 μm



#### **Electron Counting Makes All the Difference**



Single high speed frame using conventional CCD-style charge read-out



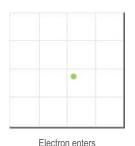
Same frame after counting



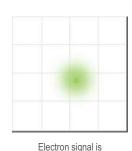
Counting removes the variability from scattering, rejects the electronic read-noise, and restores the DQE.

#### **Traditional Integration**

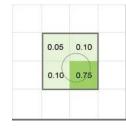
Similar to indirect detection cameras, direct detectors can integrate the total charge produced when an electron strikes a pixel.



Detector



scattered

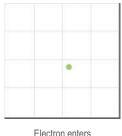


Charge collects in each pixel.

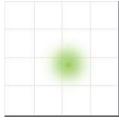


## Counting

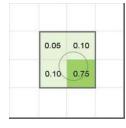
In counting mode, individual electron events are identified at the time that they reach the detector. To do this efficiently the camera must run fast enough so that individual electron events can be identified separately.



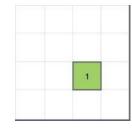
Electron enters Detector.



Electron signal is scattered.



Charge collects in each pixel.

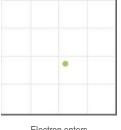


Event reduced to highest charge pixels.

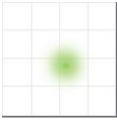


#### **Super-Resolution**

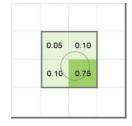
The theoretical information limit defined by the physical pixel size is surpassed when you use the K2 in super-resolution mode. The K2 sensor pixel size is slightly smaller than the area that the electron interacts with; as a result each incoming electron deposits signal in a small cluster of pixels. High-speed electronics are able to recognize each electron event (at 400 fps) and find the center of event with sub-pixel precision.



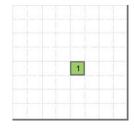
Electron enters Detector.



Electron signal is scattered.



Charge collects in each pixel.



Event localized to sub-pixel accuracy.



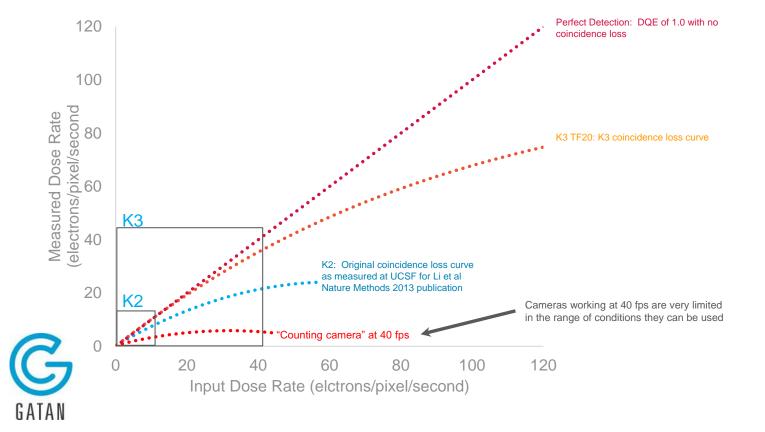
Electron Counting Requires that Electrons Don't Overlap on

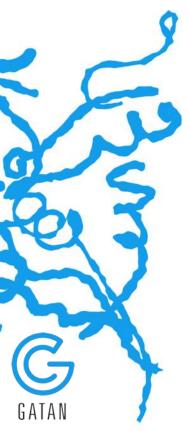
the Sensor Lower beam intensity Faster frame rate

Both methods allow counting, but the effect is not equivalent!









**Measuring Detector Performance** 

#### **PSF, MTF, NTF and DQE?**

- PSF: Point spread function
  - Blurring of a single point in the camera
- MTF: Modulation transfer function
  - PSF as a function of spatial frequency
  - Most often estimated using a "knife edge"
- NTF: Noise transfer function
  - Noise power spectrum
  - Noise as a function of spatial frequency

DQE(s)

$$= \frac{SNR_{out}(s)}{SNR_{in}(s)}$$

$$= \frac{MTF(s)^2}{NPS_{out}(s)/Dose_{in}(s)}$$



#### **DQE** Challenges

$$DQE(s)$$

$$= \frac{SNR_{out}(s)}{SNR_{in}(s)}$$

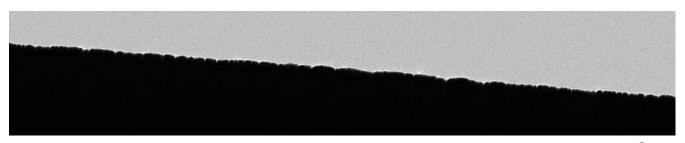
$$= \frac{SPS_{out}(s)/SPS_{in}(s)}{NPS_{out}(s)/NPS_{in}(s)}$$

$$= \frac{MTF(s)^2}{NPS_{out}(s)/Dose_{in}(s)}$$

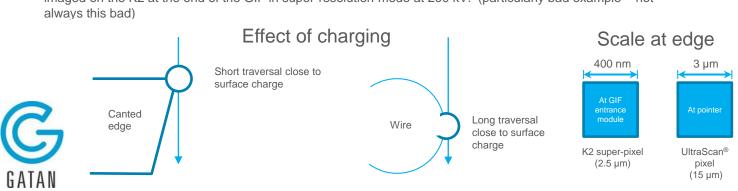


- Signal challenges: Edge image non-ideality
  - Charging and edge cleanliness
  - Scale
  - Edge dose
  - Motion
  - Fields
  - scatter
- Noise challenges:
  - Fixed pattern noise
  - Calibration of noise power
  - · Measurement of incoming beam level
- Counting-related challenges:
  - spatial effects of coincidence loss: high-pass filtering
  - Non-linear counting due to coincidence loss calibration.
  - background

# **Measuring MTF with a Physical Edge (1)**



AuPd-coated and plasma cleaned edge with canted face mounted in the entrance aperture of a GIF Quantum® imaged on the K2 at the end of the GIF in super-resolution mode at 200 kV. (particularly bad example – not always this bad)



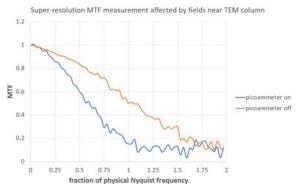
# **Measuring MTF with a Physical Edge (2)**

#### Motion – edge creep

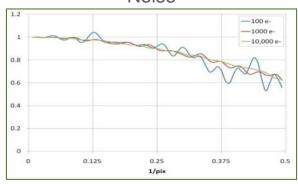


Good: difference between two 20 s edge images showing no "motion fringe".

#### Motion - fields



#### Noise

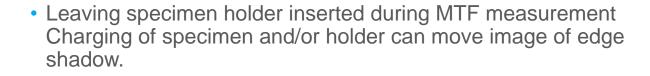


A noise-tolerant method for measuring MTF from found-object edges in a TEM, Paul Mooney, Microscopy and Microanalysis 15:1322-1323 CD Cambridge University Press (2009). Figure 4: Simulated MTF with various amounts of shot noise added.

At low dose rates, need long exposures to get enough dose → have to be careful about edge creep.

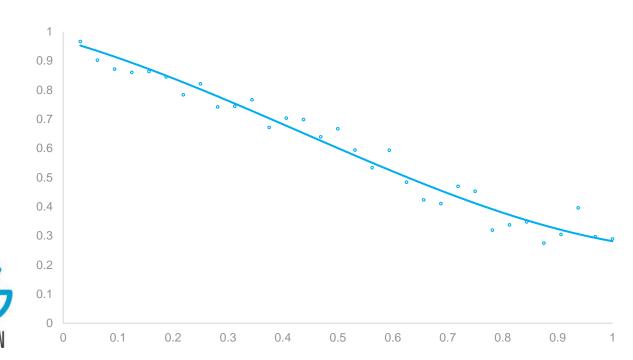
#### Other Things to Avoid with DQE Measurements

- Missing dose in a Faraday cup holder: overestimates DCE and therefore DQE (in same proportion)
- Using the TEM screen calibration
- Drifting beam current
  - Over- or under- values MTF(0) or DCE

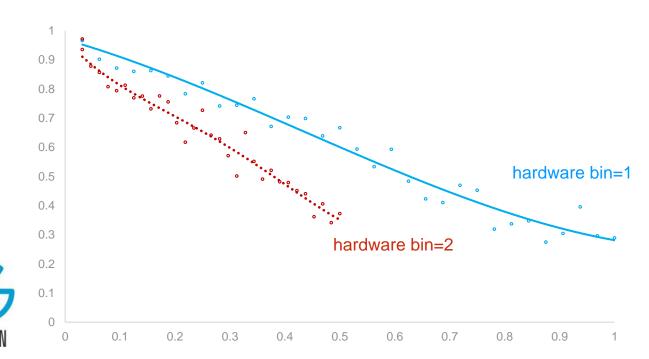




# **DQE** and Binning



# **DQE** and Binning





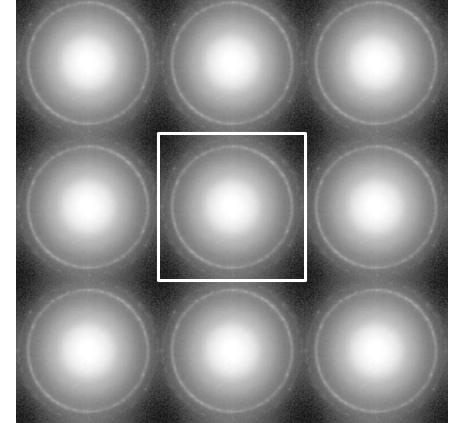








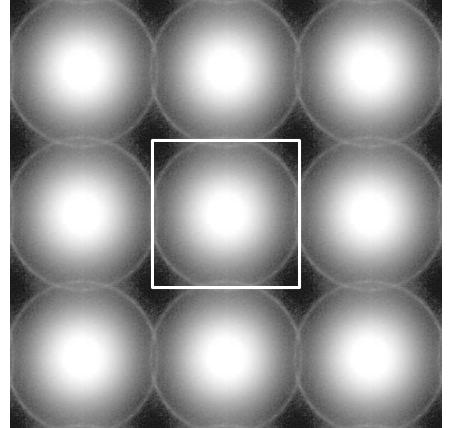




An FFT is calculated as though each image were bordered by an infinite number of neighbors

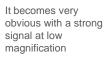


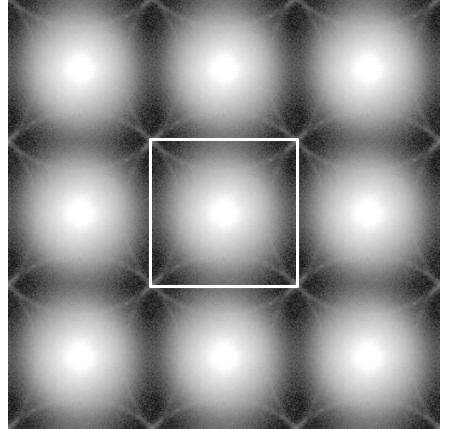






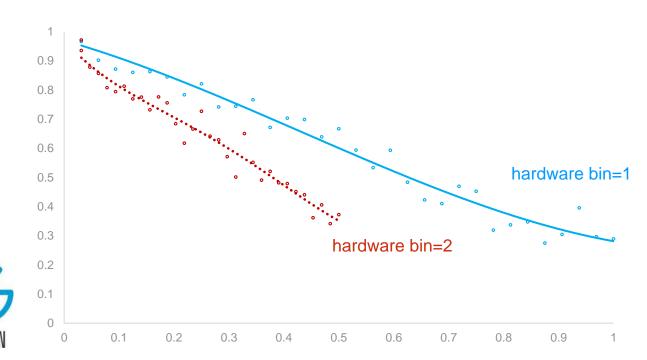




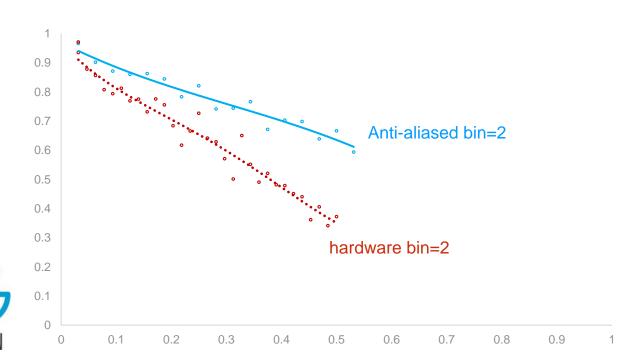




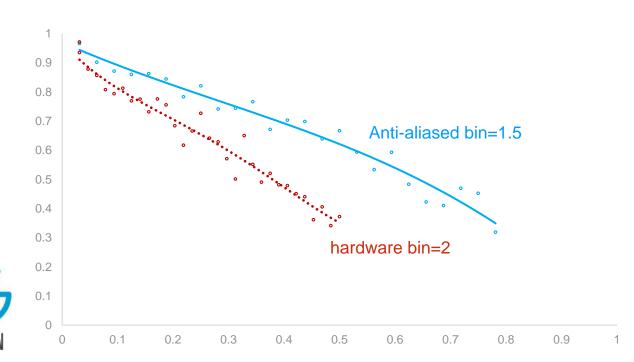
# **DQE** and Binning



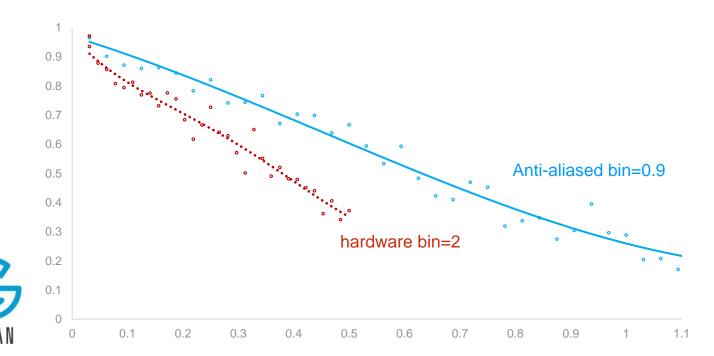
# **DQE** and Binning



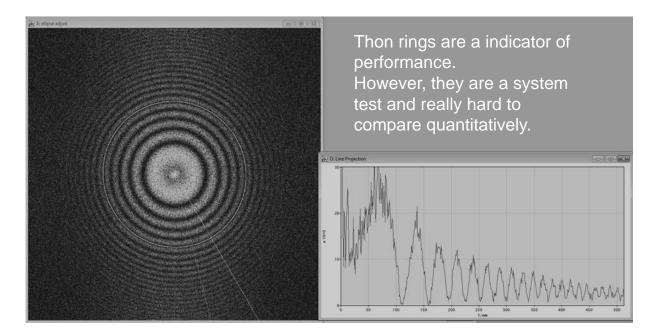
# **DQE** and Binning



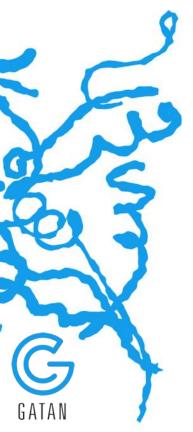
# **DQE** and Binning



## **Measuring Image Performance Using Thon Rings**



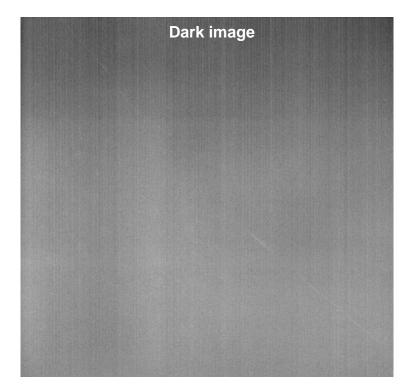




**Practical Considerations in Data Collection** 

#### **Dark Subtraction**

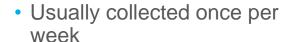
- Removes the noise baseline from the image
- New dark references are often taken once a day



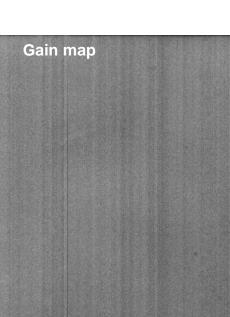


#### **Gain Correction**

- Gain correction normalizes the response of each pixel to an electron
- This is why images are often floating point values
- In K3 we are allowing integer gain normalization
  - Each electron is 32 counts



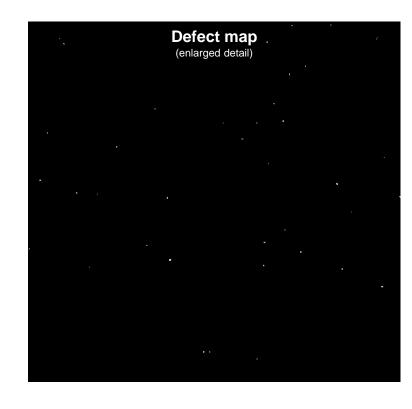




#### **Defect Correction**

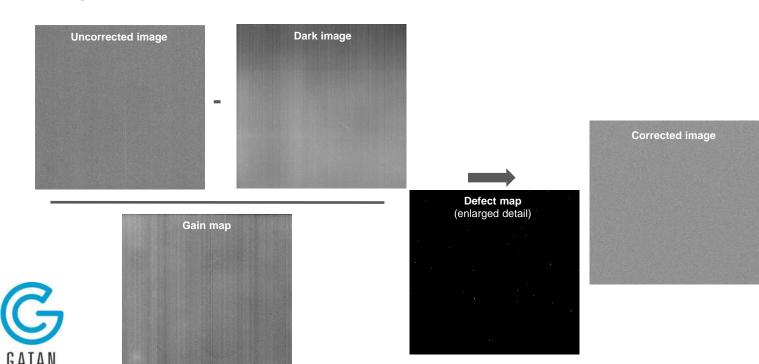
- Removes poorly performing pixels
  - Hot
  - Dark
  - Unstable
- Defect pixels contribute to fixed pattern noise

 Usually updated with Gain Reference

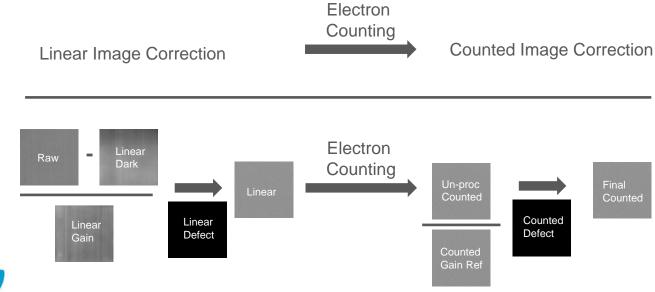




# **Typical Gain Correction Scheme**

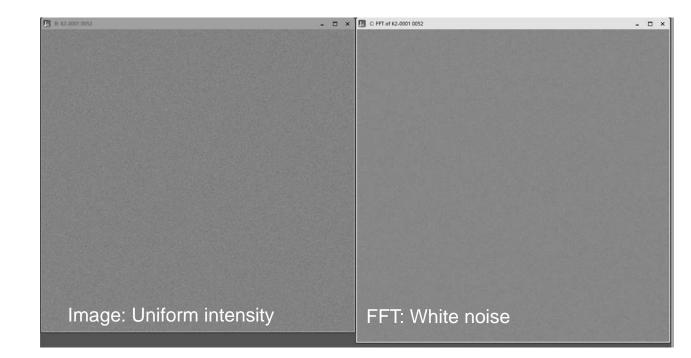


#### **Counted Gain Correction Scheme**





## **Checking the Quality of Image Correction**





## **Measurement of Fixed Pattern Noise (FPN)**

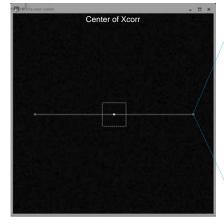
Uniform illumination

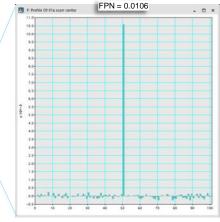
Common defects, dark image and gain image

Frame rate = 75 fr/s, (0.0133156 s/fr), all images.

Total dose = 14 e/pix, all images







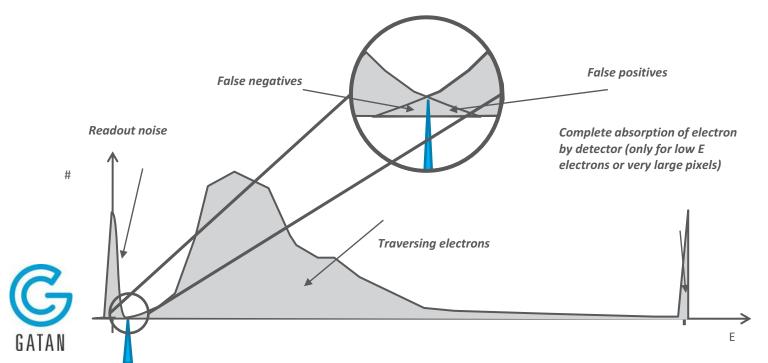


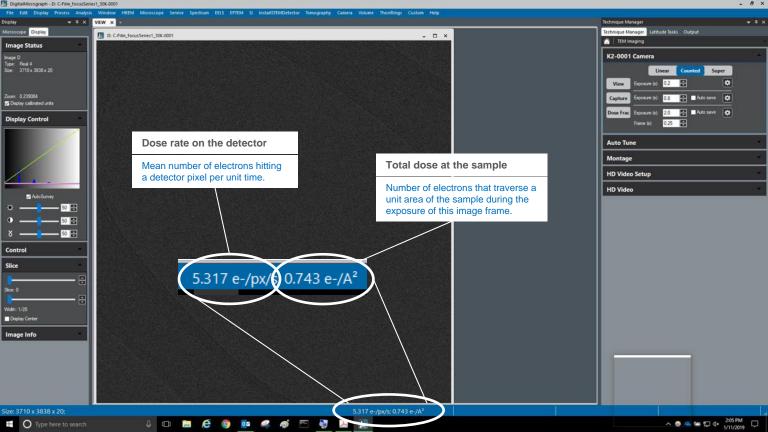
Uniform A <sup>⊗</sup> Uniform B

Cross-correlation map

FPN = peak pixel value

# Improved Noise Also Allows us to Improve Electron Countability

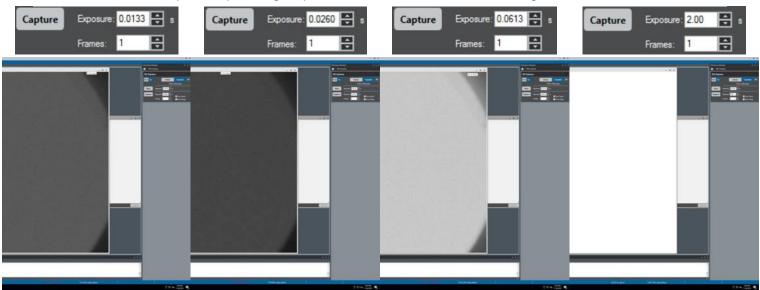




## **Keeping track of Pixel Saturation in K3**

At 8-bit/pixel, gain-corrected data saturates with a value of 255.

The saturation monitor reports the percentage of pixels that have reached saturation in a single frame.



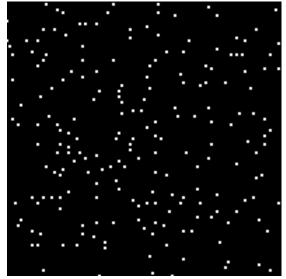
0.00% saturation

0.33% saturation

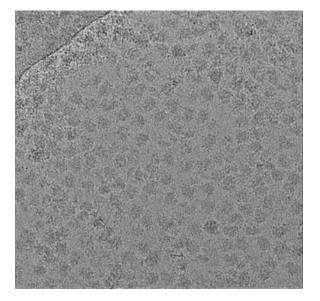
29.32% saturation

99.72% saturation

# **How Frame Alignment Works**



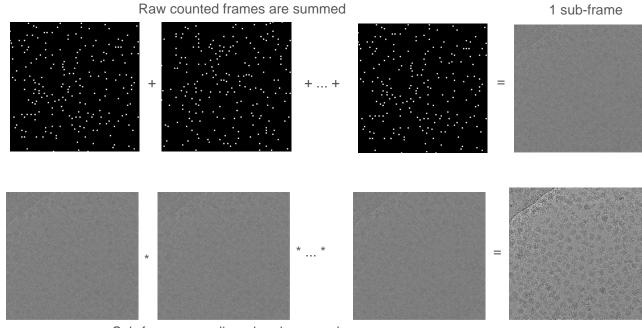






Raw counted frame

Final aligned image





Sub-frames are aligned and summed

1 final image

	Sensor Frame		Counts d France	Out from	Summed/Aligned
	Rate	Dose Rate	Counted Frame	Sub-frame	Frame
Other	40	0.8 e/pix/s	0.025 s	1 s (1 fps)	100 s
K2	400	8 e/pix/s	0.0025 s	0.1 s (10 fps)	10 s
К3	1500	30 e/pix/s	0.00066 s	0.027 s (37 fps)	2.7 s











#### MotionCor2 on the K3

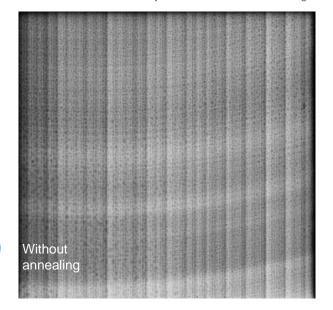
MotionCor2 -InMrc Stack.mrc -OutMrc CorrectedSum.mrc (-Patch 5 5) FtBin 1.2 Iter 10) FmDose 1.2 bft 1.1 Tol 0.5

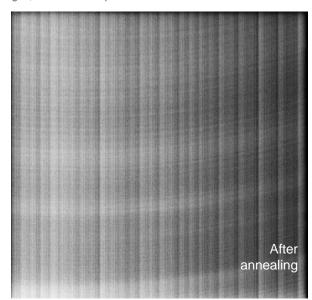




#### **Annealing Prevents Contamination Buildup**

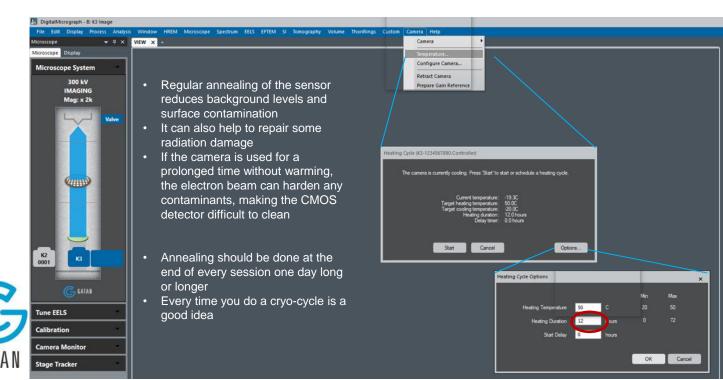
- A cold sensor is essentially a vacuum pump. Contamination builds up on its cold surface and, if left unchecked over prolonged times, will accumulate to the point of degrade data quality
- · Severe contamination may even become evident on the gain reference images, as in the example below of a K2 sensor

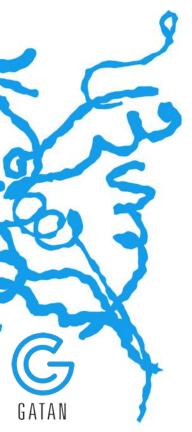






## **Camera Heating/Annealing**





**Future Directions for Electron Detection** 

## Throughput is Going to be Critical

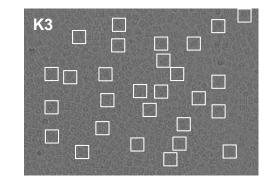
- We should be aiming to collect enough data in a few hours
- K3 + Latitude + Titan Krios

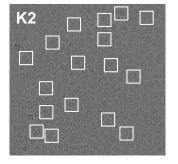




## **Improving Throughput: Larger Sensors**

- One chance to expose a specimen area
- If the pixel quality is high, larger sensors reduce the number of images needed

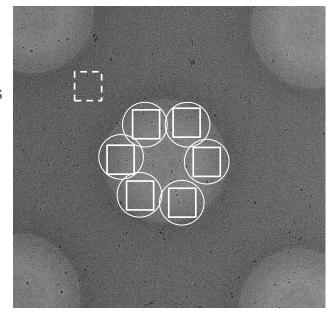






## **Improving Throughput: Faster Sensors**

- Reduce exposure times during counting
  - Exposure times: 100 s to 10 s to 1 s
- Reduce time for non-data images during automation
  - Focusing
  - Centering





## **Improving Throughput**

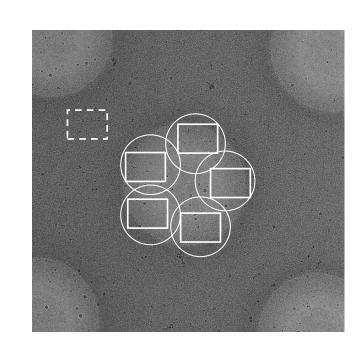
 Reducing exposure time and increasing image size gives you the biggest benefit

• K2: 6 images x 10 s = 60 s

• K3: 5 images x 2.5 s = 12.5 s

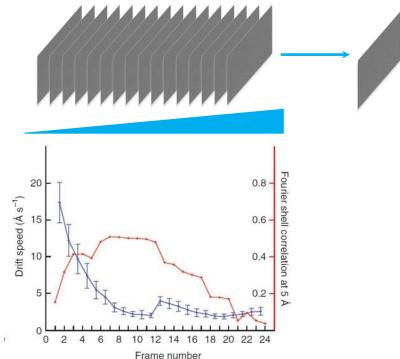
K3: area is 25% larger





**Better Data Through Motion Correction** 

- Sample damage increases during the exposure
- The first frames have the least damage but the most drift

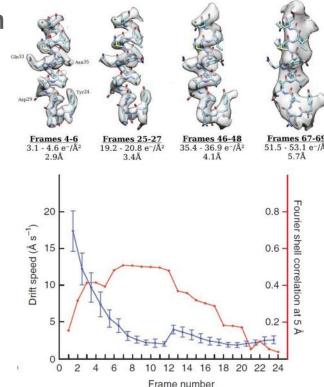




## **Better Data Through Motion Correction**

- Sample damage increases during the exposure
- The first frames have the least damage but the most drift
- Today the first 2 –3 frames are excluded
- The K3 should be fast enough to let us use frames 1 – 3!





# Thank You



